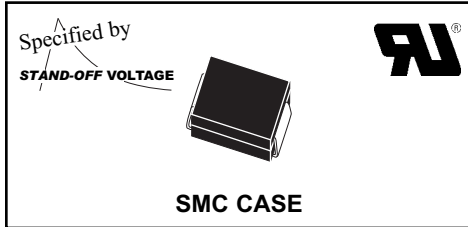


**3SMC5.0CA THRU 3SMC170CA**  
**SURFACE MOUNT BI-DIRECTIONAL**  
**GLASS PASSIVATED JUNCTION**  
**SILICON TRANSIENT**  
**VOLTAGE SUPPRESSOR**  
**3000 WATTS, 5.0 THRU 170 VOLTS**



· This series is UL listed, UL file number E130224

# Central™

**Semiconductor Corp.**

**DESCRIPTION:**

The CENTRAL SEMICONDUCTOR 3SMC5.0CA Series types are Surface Mount Bi-Directional Glass Passivated Junction Transient Voltage Suppressors designed to protect voltage sensitive components from high voltage transients.

**THIS DEVICE IS MANUFACTURED WITH A GLASS PASSIVATED CHIP FOR OPTIMUM RELIABILITY.**

Note: For Uni-directional devices, please refer to the 3SMC5.0A Series data sheet.

**MARKING CODE: SEE MARKING CODE ON ELECTRICAL CHARACTERISTIC TABLE**

**MAXIMUM RATINGS:** ( $T_A=25^\circ\text{C}$  unless otherwise noted)

Peak Power Dissipation (Note 1)  
 Peak Forward Surge Current (JEDEC Method)  
 Operating and Storage Junction Temperature

SYMBOL		UNITS
$P_{DM}$	3000	W
$I_{FSM}$	200	A
$T_J, T_{stg}$	-65 to +150	$^\circ\text{C}$

**ELECTRICAL CHARACTERISTICS:** ( $T_A=25^\circ\text{C}$  unless otherwise noted)

TYPE	REVERSE STAND-OFF VOLTAGE	BREAKDOWN VOLTAGE ( $V_{BR} @ I_T$ )		TEST CURRENT	MAXIMUM REVERSE LEAKAGE	MAXIMUM CLAMPING VOLTAGE	PEAK PULSE CURRENT (Note 1)	MARKING CODE
	$V_{RWM}$	MIN	MAX	$I_T$	$I_R @ V_{RWM}$	$V_C @ I_{PP}$	$I_{PP}$	
	V	V	V	mA	$\mu\text{A}$	V	A	
3SMC5.0CA	5.0	6.40	7.25	10	2000	9.2	326.0	CIDE
3SMC6.0CA	6.0	6.67	7.67	10	2000	10.3	291.3	CIDG
3SMC6.5CA	6.5	7.22	8.30	10	1000	11.2	267.9	CIDK
3SMC7.0CA	7.0	7.78	8.95	10	400	12.0	250.0	CIDM
3SMC7.5CA	7.5	8.33	9.58	1.0	200	12.9	232.6	CIDP
3SMC8.0CA	8.0	8.89	10.23	1.0	100	13.6	220.6	CIDR
3SMC8.5CA	8.5	9.44	10.82	1.0	50	14.4	208.4	CIDT
3SMC9.0CA	9.0	10.0	11.5	1.0	20	15.4	194.8	CIDV
3SMC10CA	10	11.1	12.8	1.0	5.0	17.0	176.4	CIDX
3SMC11CA	11	12.2	14.0	1.0	5.0	18.2	184.8	CIDZ
3SMC12CA	12	13.3	15.3	1.0	5.0	19.9	150.6	CIEE
3SMC13CA	13	14.4	16.5	1.0	5.0	21.5	139.4	CIEG
3SMC14CA	14	15.6	17.9	1.0	5.0	23.2	129.4	CIEK
3SMC15CA	15	16.7	19.2	1.0	5.0	24.4	123.0	CIEM
3SMC16CA	16	17.8	20.5	1.0	5.0	26.0	115.4	CIEP
3SMC17CA	17	18.9	21.7	1.0	5.0	27.6	106.6	CIER
3SMC18CA	18	20.0	23.3	1.0	5.0	29.2	102.8	CIET
3SMC20CA	20	22.2	25.5	1.0	5.0	32.4	92.6	CIEV
3SMC22CA	22	24.4	28.0	1.0	5.0	35.5	84.4	CIEX
3SMC24CA	24	26.7	30.7	1.0	5.0	38.9	77.2	CIEZ
3SMC26CA	26	28.9	33.2	1.0	5.0	42.1	71.2	CIFE
3SMC28CA	28	31.1	35.8	1.0	5.0	45.4	66.0	CIFG
3SMC30CA	30	33.3	38.3	1.0	5.0	48.4	62.0	CIFK

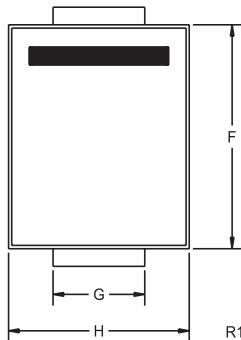
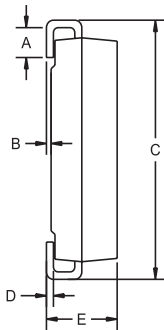
Notes: (1) Non-repetitive 10x1,000 $\mu\text{s}$  pulse

R4 (3-March 2008)

**ELECTRICAL CHARACTERISTICS - Continued:**

TYPE	REVERSE STAND-OFF VOLTAGE	BREAKDOWN VOLTAGE (V <sub>BR</sub> @ I <sub>T</sub> )		TEST CURRENT	MAXIMUM REVERSE LEAKAGE	MAXIMUM CLAMPING VOLTAGE	PEAK PULSE CURRENT (Note 1)	MARKING CODE
	V <sub>RWM</sub>	MIN	MAX	I <sub>T</sub>	I <sub>R</sub> @ V <sub>RWM</sub>	V <sub>C</sub> @ I <sub>PP</sub>	I <sub>PP</sub>	
	V	V	V	mA	μA	V	A	
3SMC33CA	33	36.7	42.2	1.0	5.0	53.3	56.2	CIFM
3SMC36CA	36	40.0	46.0	1.0	5.0	58.1	51.6	CIFP
3SMC40CA	40	44.4	51.1	1.0	5.0	64.5	46.4	CIFR
3SMC43CA	43	47.8	54.9	1.0	5.0	69.4	43.2	CIFT
3SMC45CA	45	50.0	57.5	1.0	5.0	72.7	41.2	CIFV
3SMC48CA	48	53.3	61.3	1.0	5.0	77.4	38.8	CIFX
3SMC51CA	51	56.7	65.2	1.0	5.0	82.4	36.4	CIFZ
3SMC54CA	54	60.0	69.0	1.0	5.0	87.1	34.4	CIGE
3SMC58CA	58	64.4	74.1	1.0	5.0	93.6	32.0	CIGG
3SMC60CA	60	66.7	76.7	1.0	5.0	96.8	31.0	CIGK
3SMC64CA	64	71.1	81.8	1.0	5.0	103	29.2	CIGM
3SMC70CA	70	77.8	89.5	1.0	5.0	113	26.6	CIGP
3SMC75CA	75	83.3	95.8	1.0	5.0	121	24.8	CIGR
3SMC78CA	78	86.7	99.7	1.0	5.0	126	22.8	CIGT
3SMC85CA	85	94.4	108.2	1.0	5.0	137	20.8	CIGV
3SMC90CA	90	100.0	115.5	1.0	5.0	146	20.6	CIGX
3SMC100CA	100	111.0	128.0	1.0	5.0	162	18.6	CIGZ
3SMC110CA	110	122.0	140.5	1.0	5.0	177	16.8	CIHE
3SMC120CA	120	133.0	153.0	1.0	5.0	193	15.6	CIHG
3SMC130CA	130	144.0	165.5	1.0	5.0	209	14.4	CIHK
3SMC150CA	150	167.0	192.5	1.0	5.0	243	12.4	CIHM
3SMC160CA	160	178.0	205.0	1.0	5.0	259	11.6	CIHP
3SMC170CA	170	189.0	217.5	1.0	5.0	275	11.0	CIHR

**SMC - CASE - MECHANICAL OUTLINE**

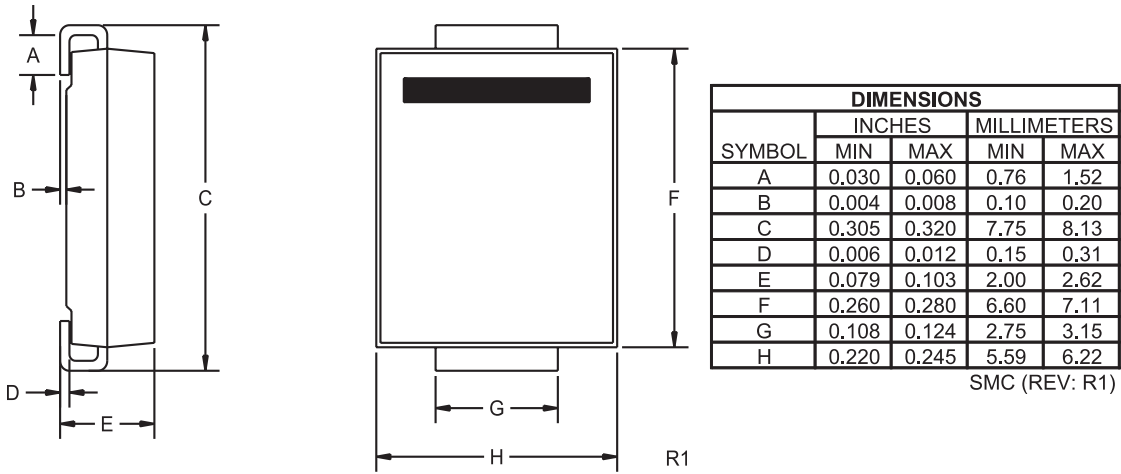


SYMBOL	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.030	0.060	0.76	1.52
B	0.004	0.008	0.10	0.20
C	0.305	0.320	7.75	8.13
D	0.006	0.012	0.15	0.31
E	0.079	0.103	2.00	2.62
F	0.260	0.280	6.60	7.11
G	0.108	0.124	2.75	3.15
H	0.220	0.245	5.59	6.22

SMC (REV: R1)

# Package Details - SMC

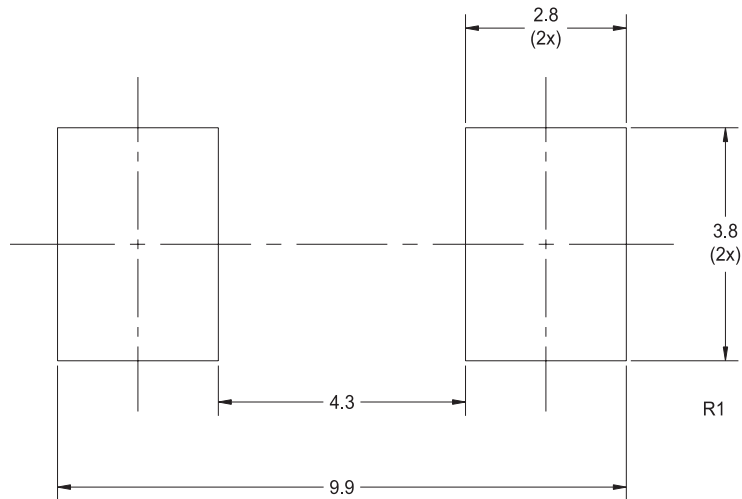
## Mechanical Drawing



**Lead Code:**  
Reference individual device datasheet.

**Part Marking:** 3-6 Character Alpha/Numeric Code

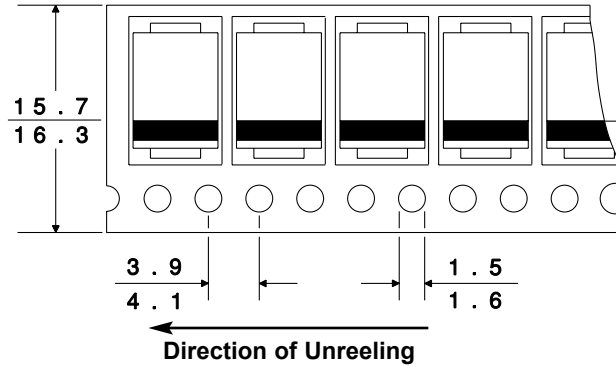
## Mounting Pad Geometry (Dimensions in mm)



# Package Details - SMC

## Tape Dimensions and Orientation (Dimensions in mm.)

Tape Width: 16mm



\* Devices are taped in accordance with Electronic Industries Association Standard EIA-481-2-A

## Packaging Base

13" Reel = 3,000 pcs. (add TR13 suffix to part number)  
Bulk = 100 pcs. (add BK suffix to part number)

## Reel Labeling Information

Each reel is labeled with the following information:

Central Part Number, Customer Part Number, Purchase Order Number, Quantity, Lot Number, Date Code, Ship Date and Marking Code.

## Reel Packing Information

Reel Size	Quantity Per Box	Number of Reels per Box	Box Dimensions		Shipping Weight	
			INCH	CM	LB	KG
13"	39,000	13	14x14x8	36x36x20	22	10

## Ordering Information

- For devices taped and reeled on 13" reels, add TR13 suffix to part number.
- For devices bulk packed, add BK suffix to part number.
- All SMDs are available bulk packed, for prototype and manual placement applications.

R1 (10-December 2002)

**Central**<sup>TM</sup>  
Semiconductor Corp.  
www.centalsemi.com

# Material Composition Specification

SMC Case

Pb (lead)-free plating\*\*



Device average mass ..... **232.5 mg**

Fluctuation margin ..... **+/-10%**

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	1.63%	3.8	Si	7440-21-3	1.6%	3.8	16,000
leadframe	copper	39.107%	90.92	Cu	7440-50-8	39.107%	90.92	391,070
die attach	high temperature solder paste	1.875%	4.36	Pb	7439-92-1	1.735%	4.033	17,350
				Sn	7440-31-5	0.094%	0.218	940
				Ag	7440-22-4	0.047%	0.109	470
encapsulation*	EMC	56.77%	132	silica	7631-86-9	38.606%	89.76	386,060
				epoxy resin	Proprietary	17.032%	39.6	170,320
				Sb <sub>2</sub> O <sub>3</sub>	1309-64-4	0.568%	1.32	5,680
				TBBA	79-94-7	0.568 %	1.32	5,680
	EMC GREEN	56.77 %	132	silica	7631-86-9	39.39%	91.592	393,942
				epoxy resin	Proprietary	17.38%	40.408	173,798
plating**	tin lead process	0.661%	1.419	Sn	7440-31-5	0.529%	1.135	5,290
				Pb	7439-92-1	0.132%	0.335	1,320
	100% tin process	0.661%	1.419	Sn	7440-31-5	0.77%	0.708	7,700

\*EMC GREEN molding compound is Halogen-Free.

\*\*Specify Lead-Free when ordering 100% tin (Pb-free) plating.

Disclaimer

The information provided in this Material Composition data sheet is, to our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.